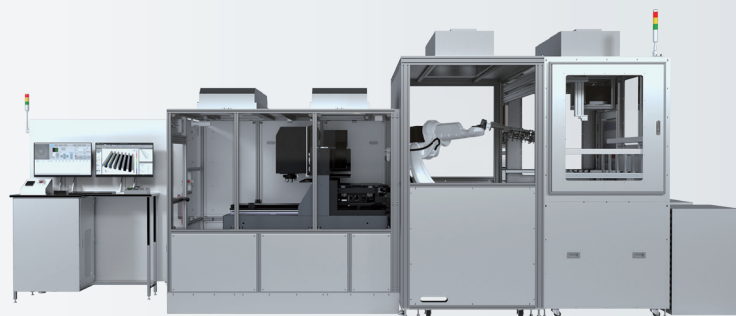
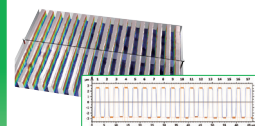


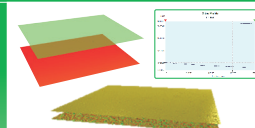
次世代基板対応、高速・高精度3次元計測装置
High-speed, high-precision 3D measurement system compatible with next-generation substrates



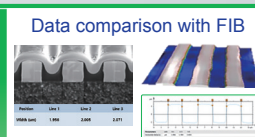
深さ5 μ m、
Line Space 2/2対応
Depth 5 μ m, compatible with
Line Space 2/2



透過測定法による
SR・ABFの厚さ測定
Transmission measurement
method for SR/ABF



ガラスコア対応可能な
技術力と信頼
Reliable technical capabilities
in Glass-core applications



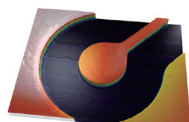
仕様 | Specifications

Type of Part	Items	Specifications
3D Head	測定方法 Measuring Method	White-Light Scanning Interferometry Coherent Scanning Interferometer (F-CSI) Phase Shift Interferometry (PSI) Thick film measurement
	パネルサイズ Panel Size	Max. 510mm x 610mm
	スキャンスピード Vertical Scan Speed	Max. 65 μ m/s
	スキャンレンジ Vertical Scan Range	$\leq 270\mu$ m
	解像度 Vertical Resolution	WSI < 0.5nm, PSI < 0.1nm, Fast CSI < 1.5nm
	繰り返し精度 Vertical Repeatability	$\leq 0.1\%$ @ 1σ (VLSI 7.969 μ m ± 0.065 , Repeat 16 times)
	スキャン動作 Scan Actuator	Closed-Loop Controlled Piezo Actuator
	照明 Illumination	White LED Illumination
	レンズ Lens Turret	Motorized nosepiece turret 5 Lens available (i5x, i10x, i20x, i50x / 5x, 10x)
	F.O.V. Turret	x0.55, x0.75, x1.0, x1.5, x2.0 (4 FOV Lens Available)
SR&ABF Thickness Module	スキャンスピード Vertical Scan Speed	48.9 μ m/s
	スキャンレンジ Vertical Scan Range	$\leq 270\mu$ m
	解像度 Vertical Resolution	WSI < 0.5nm
	繰り返し精度 Vertical Repeatability	< 1 μ m 3 σ , Measuring Samples (SR and ABF)
	スキャン動作 Scan Actuator	Closed-Loop Controlled Piezo Actuator
	レンズ Tube Lens	x2.0
	レンズ NIR Lens	x20

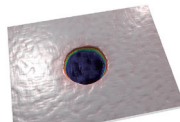
測定機能 | Measuring Items



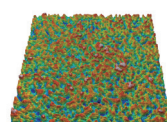
Trace



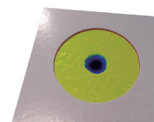
Pad



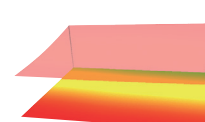
Via



Anchor



Overlay



Film